

## Version With Markings To Show Changes Made

1. (Three Times Amended) A method comprising:

placing an incomplete chip package into a mold formed by a first portion and a second portion, the incomplete chip package comprising a chip and a substrate electrically coupled using a flip chip process, the mold having an upper inner surface [in] which [its entire length] is coated with release film, and the chip having (i) a top surface facing the substrate, (ii) a bottom surface opposite the top surface, the bottom surface butting against the upper inner surface, and (iii) one or more side surfaces between the top and bottom surfaces;

injecting a liquid resin into a runner section of the mold, the runner formed by mating [between a] the first portion [and] with the second portion, and the resin encapsulating a significant portion of the one or more side surfaces, and filling a first gap between the top surface and the adjacent substrate; and

curing the resin.

20. (Three Times Amended) A method comprising:

placing an incomplete flip chip package into a bottom inner cavity of a bottom mold portion, the incomplete flip chip package comprising a chip and a substrate, the chip having a top surface coupled by reflowed solder bumps to an upper surface of the substrate, the

chip further comprising a bottom surface opposite the top surface and one or more side surfaces between the top and bottom surfaces;

mating an upper mold portion with the lower mold portion, the upper mold portion having an upper inner cavity, including an upper inner surface [in] which [its entire length] is coated with a release film, and the bottom surface of the chip butts against the upper inner surface, the upper and bottom inner cavities forming a mold inner cavity enclosing the incomplete flip chip package, and forming a runner between the upper and lower mold portions[.];

injecting a predetermined amount of a liquid resin into the mold inner cavity through the runner, the liquid resin encapsulating substantially all or the one or more side surfaces and substantially all of the upper surface, the liquid resin further filling a gap between the top surface of the chip and an adjacent portion of the upper surface of the substrate, encapsulating the reflowed solder bumps; and

curing the liquid resin by maintaining the mold at an elevated temperature for a predetermined period of time, the elevated temperature being equal to or greater than the cure temperature of the filled liquid resin for the predetermined period of time.

35. (Cancelled)

36. (Cancelled)